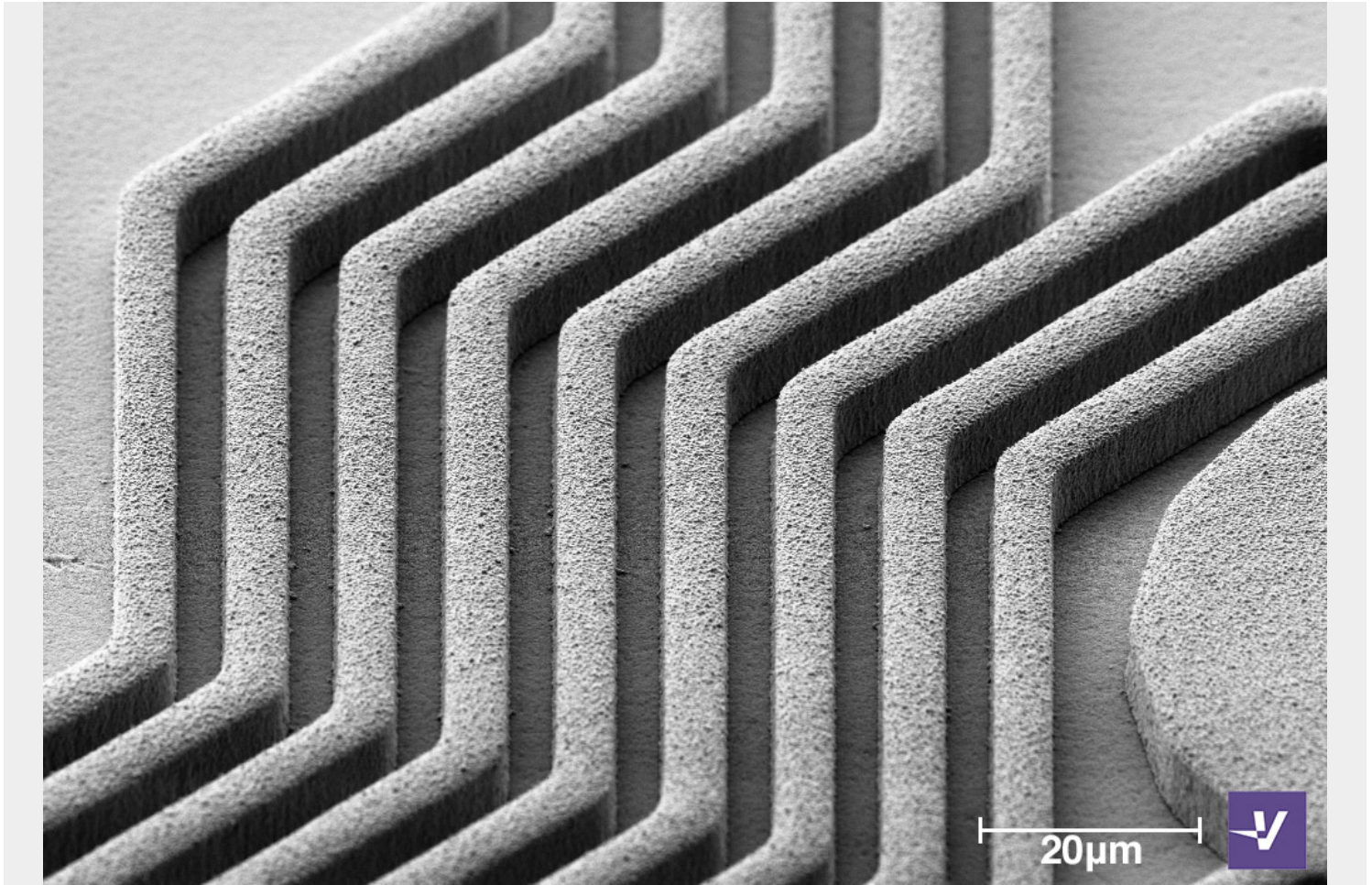
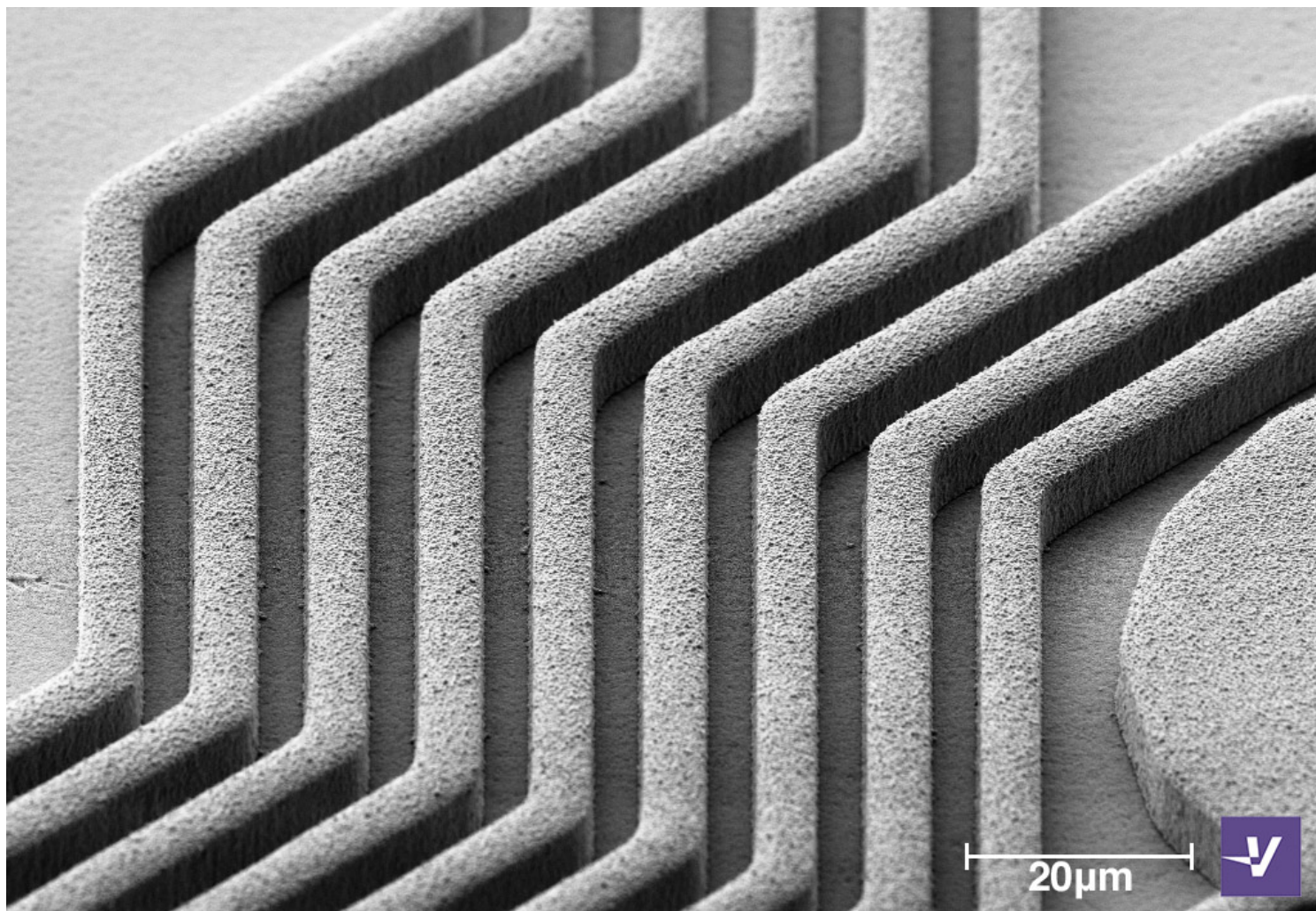


MOVING ADVANCED PACKAGING FORWARD: VISITECH SPONSORS SYNAPS 2021

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Visitech's strong focus on developing high-end subsystems for advanced packaging allows toolmakers to innovate better products more efficiently. Being the key driver and enabler for the electronics value chain, advanced packaging is essential to the semiconductor industry.



With rapid development, learning what new product offerings are available and which direction development is taking is key for tomorrow's industry to stay on top of innovation. A useful forum where leading companies can gain such insight is SYNAPS (*Symposium by Yole Développement and NCAP on Advanced Packaging Semiconductors*). This is why Visitech will be a Gold Sponsor of the 2021 SYNAPS symposium, an online event that takes place on May 18-20, 2021.

– We look forward to the event and trust that participants will find Visitech's LUXBEAM® Lithography system, which enables better yield and precision, not only interesting but also instrumental when planning their next-generation direct imaging lithography solutions for advanced packaging, states Managing Director at Visitech, Øyvind Tafjord.

Find out more about the event [here](#).